pSemi A Murata Company

ULTRACMOS® GREEN

pSEMI MATERIAL DECLARATION FORM

Product:	**PE42546**
Ordering Codes:	**PE42546A-Z**
Description:	**PE42546 SP4T RF Switch**
Package:	**20-lead 3x3 mm LGA**
Environmental Compliance	EU **RoHS** Directive 2011/65/EC and amendment 2015/863, **REACH** - EU ECHA SVHC, **Arsenic Free**, **JIG 101** - EIA/EICTA/JEITA, **Halogen Free** - IEC61249-2-21, **PFOS Free** - 2006/122/EC, **Antimony Trioxide Free**
Lead Finish	**Solder Bump**
Availability	**Now**

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Silicon	7440-21-3	4.516800	21.15%	211,471.73
Die	Phosphorus	7723-14-0	0.000023	0.00%	1.06
Die	Boron	7440-42-8	0.000023	0.00%	1.06
Die	Arsenic	7440-38-2	0.000023	0.00%	1.06
Die	Germanium	7440-56-4	0.000023	0.00%	1.06
Die	Indium	7440-74-6	0.000023	0.00%	1.06
Die	Cobalt	7440-48-4	0.000023	0.00%	1.06
Die	Tungsten	7440-33-7	0.000850	0.00%	39.79
Die	Copper	7440-50-8	0.025776	0.12%	1,206.81
Die	Tantalum	7440-25-7	0.001223	0.01%	57.24
Die	Aluminum	7429-90-5	0.000473	0.00%	22.13
Polyimide	Proprietary polymer	-	0.000021	0.00%	1.00
Sputter	Titanium	7440-32-6	0.000086	0.00%	4.01
Sputter	Tungsten	7440-33-7	0.000086	0.00%	4.01
Sputter	Copper	7440-50-8	0.000171	0.00%	8.03
Sputter	Nickel	7440-02-0	0.001800	0.01%	84.27
UBM	Copper	7440-50-8	0.001600	0.01%	74.91
Solder Bump	Tin	7440-31-5	0.019368	0.09%	906.81
Solder Bump	Silver	7440-22-4	0.000355	0.00%	16.62
Substrate	Copper	7440-50-8	2.882841	13.50%	134,971.54
Substrate	Nickel	7440-02-0	0.073313	0.34%	3,432.42
Substrate	Palladium	7440-05-3	0.005446	0.03%	254.96
Substrate	Gold	7440-57-5	0.005968	0.03%	279.41
Substrate	Continuous Filament Fiber Glass	65997-17-3	0.820800	3.84%	38,428.97
Substrate	Thermosetting resin(Including inorganic filler)	-	0.889200	4.16%	41,631.39
Substrate	Formaldehyde polymer with (chloromethyl)oxirane and 4,4'-(1-methylethylidene)bis[phenol]	28906-96-9	0.157800	0.74%	7,388.03
Substrate	2,4,6-trimethylbenzoyldiphenylphosphineoxide/Diphenyl(2,4,6-trimethylbenzoyl)phosphineoxide	75980-60-8	0.078849	0.37%	3,691.61
Substrate	2-[[3-[(1-Oxoallyl)oxy]-2,2-bis[[(1-oxoallyl)oxy]methyl]propoxy]methyl]-2-[[(1-oxoallyl)oxy]methyl]-1,3-propanediyldiacrylate	29570-58-9	0.078849	0.37%	3,691.61
Substrate	2-[[3-Hydroxy-2,2-bis[[(1-oxoallyl)oxy]methyl]propoxy]methyl]-2-[[(1-oxoallyl)oxy]methyl]-1,3-propanediyldiacrylate	60506-81-2	0.078849	0.37%	3,691.61
Substrate	TALC, (containing no Asbestos fibres)	14807-96-6	0.078849	0.37%	3,691.61

Substrate	1,3,5-Triazine-2,4,6-triamine	108-78-1	0.039476	0.18%	1,848.21
Mold Compound	Solid Epoxy Resin	-	0.695994	3.26%	32,585.69
Mold Compound	Hardener	-	0.463996	2.17%	21,723.79
Mold Compound	Carbon Black	1333-86-4	0.115999	0.54%	5,430.95
Mold Compound	Metal Hydroxide	-	0.231998	1.09%	10,861.90
Mold Compound	Amorphous silica	60676-86-0	10.091913	47.25%	472,492.52
Total Weight (mg)			**21.358884**	100.00%	1,000,000